

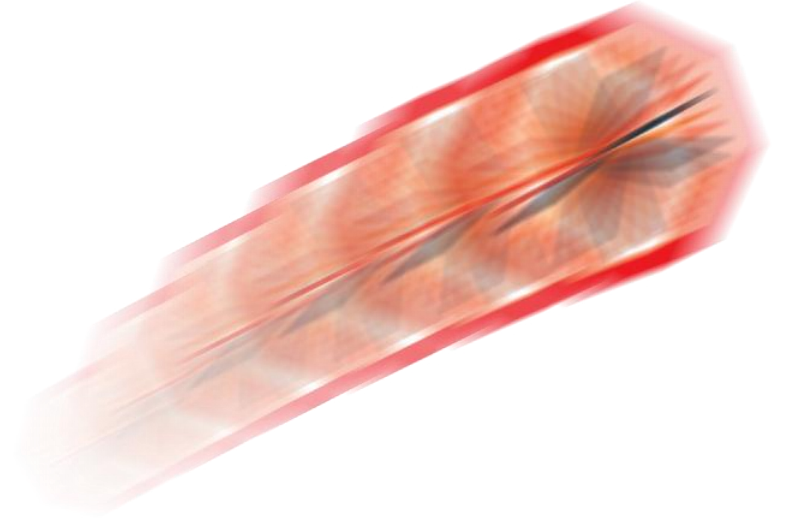
Fast Interaction Trigger (FIT)

X. Y.

on behalf of FIT Collaboration

March 2014

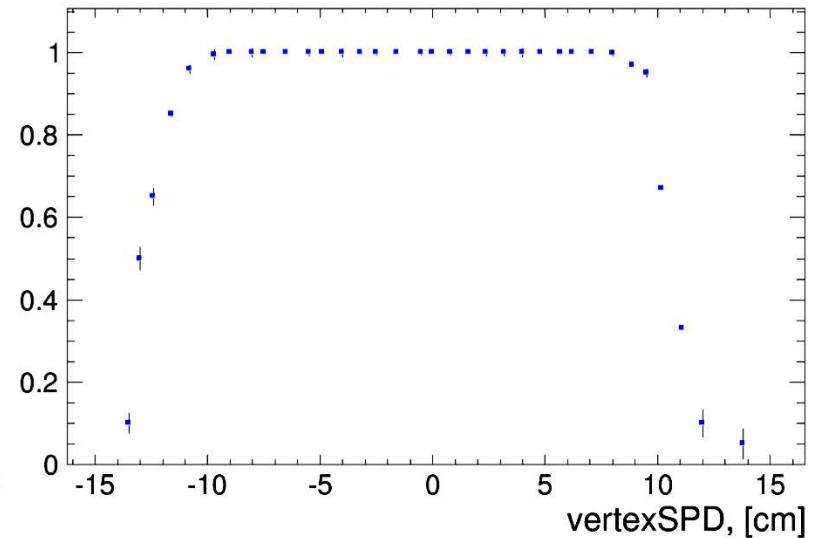
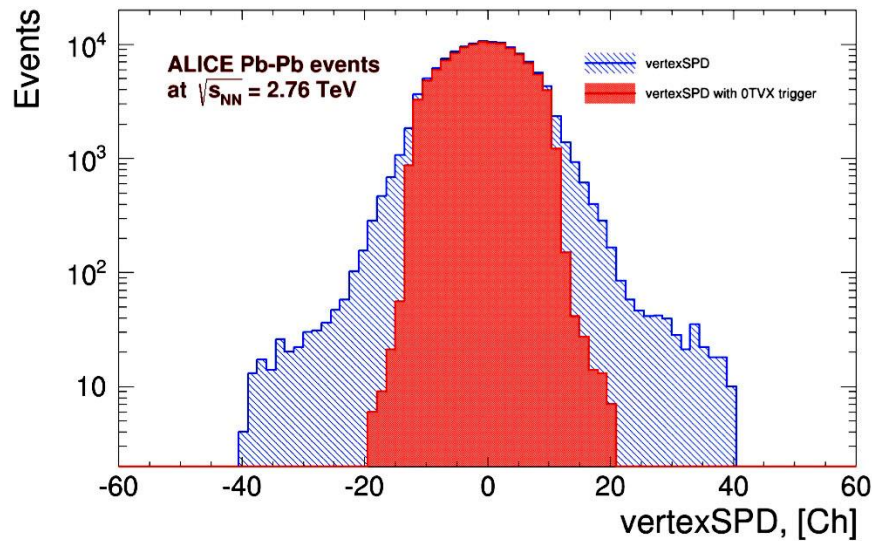
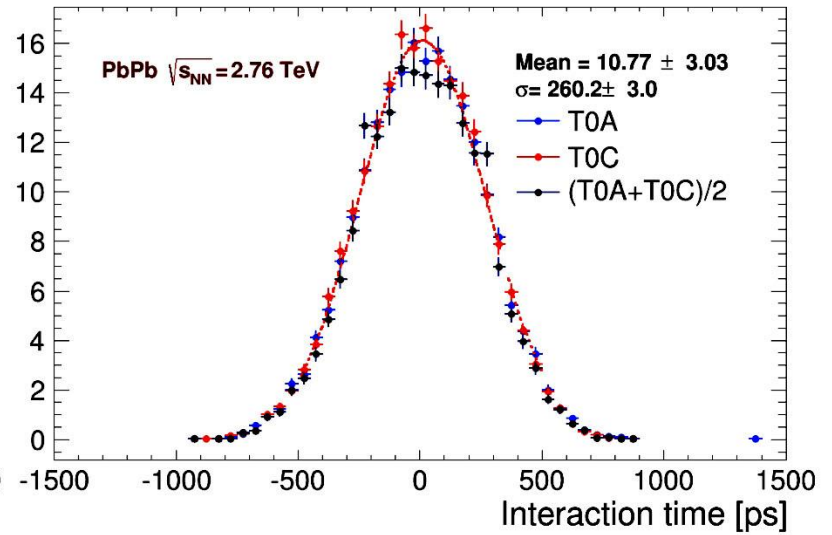
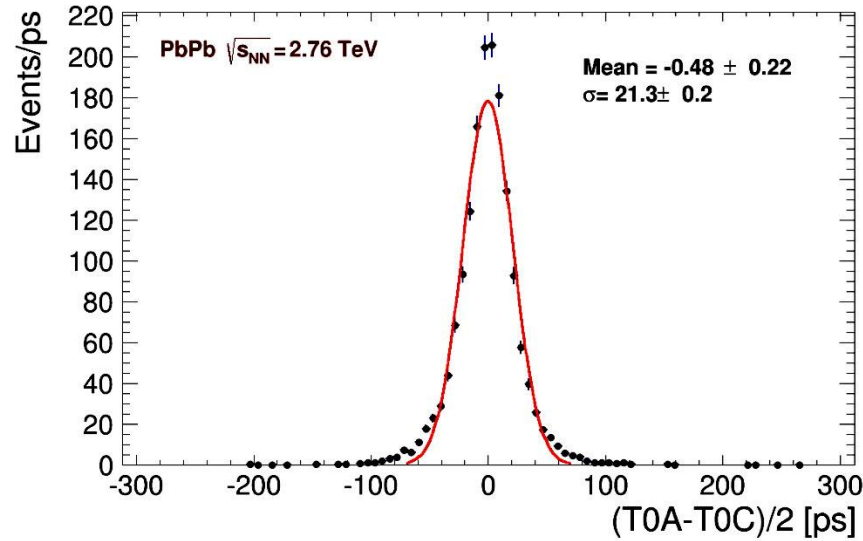
Outline



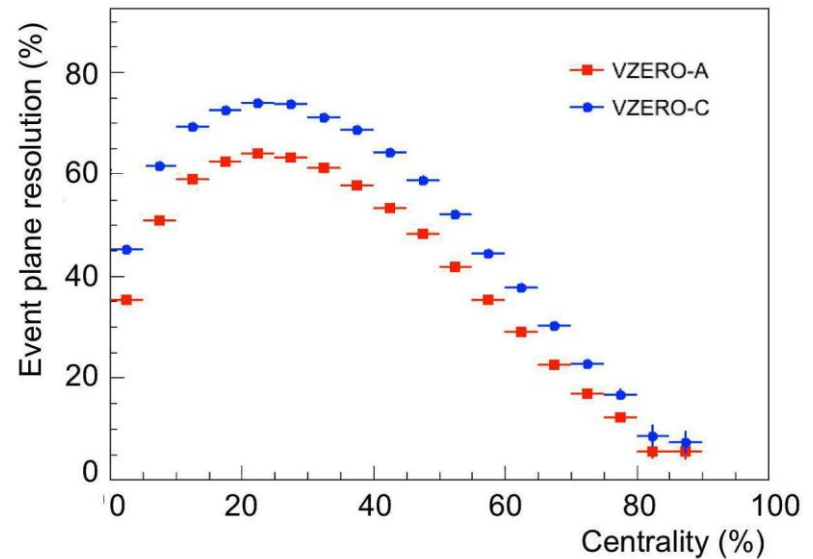
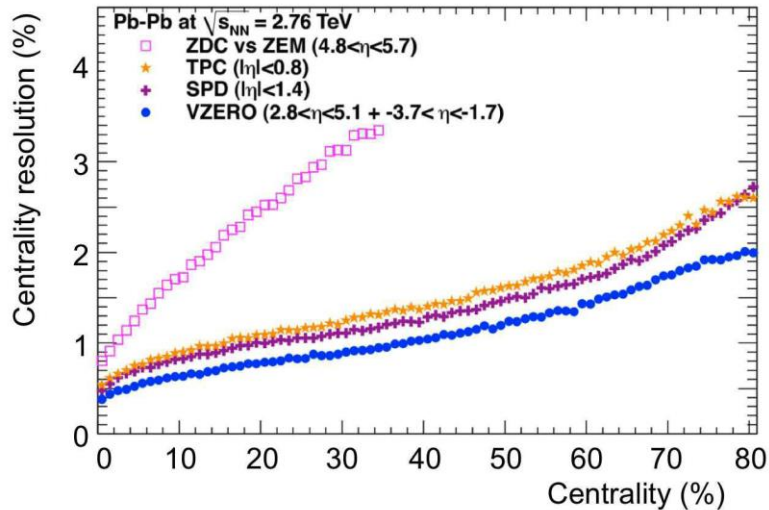
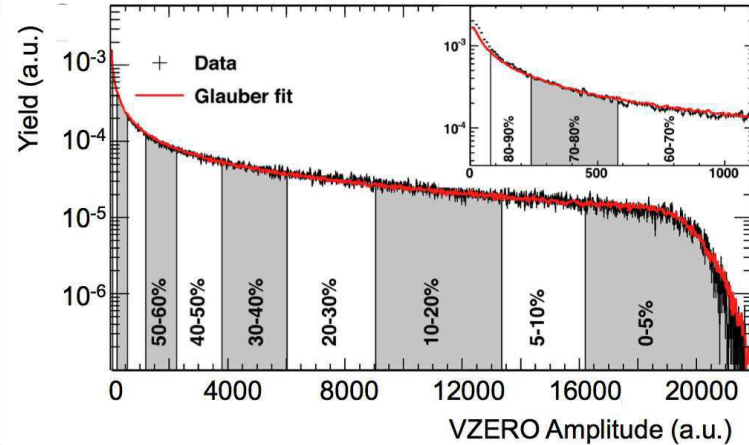
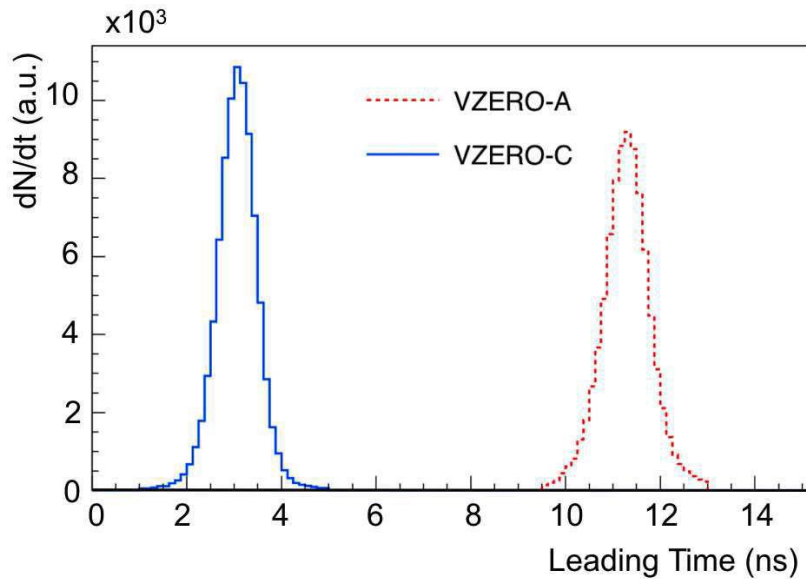
Required functionality for FIT @ Run3

- Minimum Bias trigger for pp collisions with efficiency comparable to the current V0: 83 % for vertex (A&C) and 93% for the OR signal (A|C).
- Event Multiplicity determination capable of selecting and triggering on central as well as on semi-central collisions. The centrality selection should match the performance of the present V0.
- Vertex location with a performance comparable to the present T0 system.
- Evaluation and rejection of beam-induced background and in particular beam gas event sensitivity on the level of the current V0 detector.
- Time resolution better than 50 ps for pp collisions, as in the present T0 system.
- Determination of collision time for TOF with resolution better than 50 ps.
- Event plane determination with a precision similar to the present V0 system.
- Minimal ageing over the ALICE operation period.
- No after pulses or other spurious signals.
- Direct feedback to LHC on luminosity and beam conditions.

T0 performance during Run1

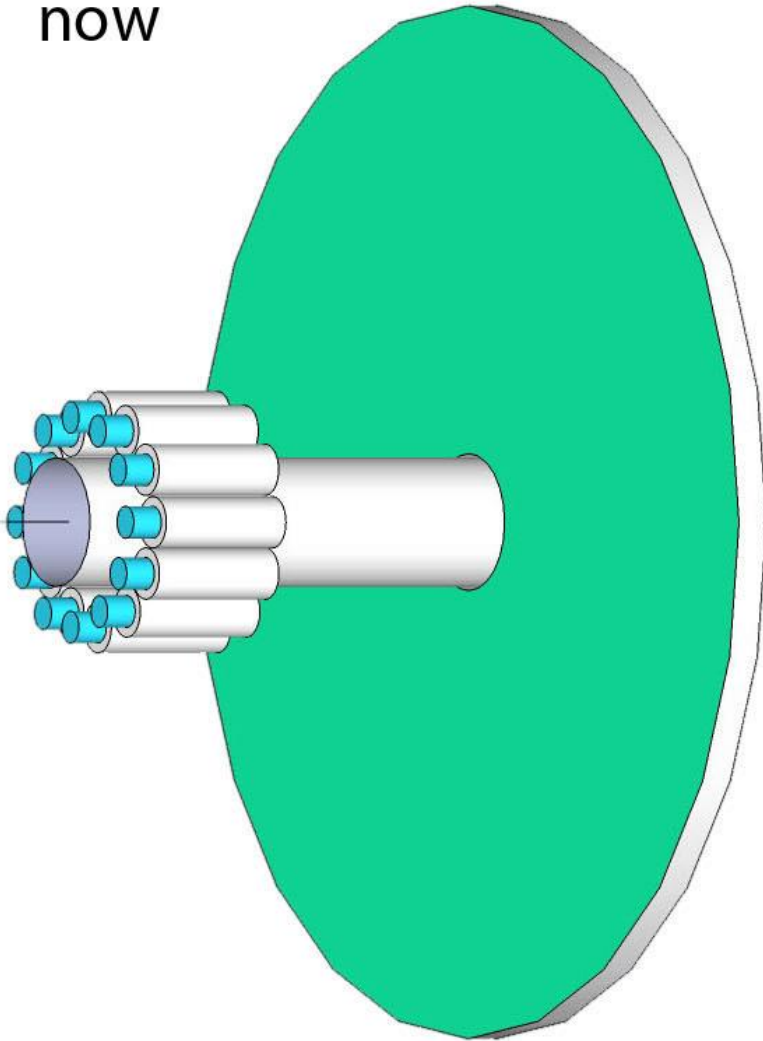


V0 performance during Run1

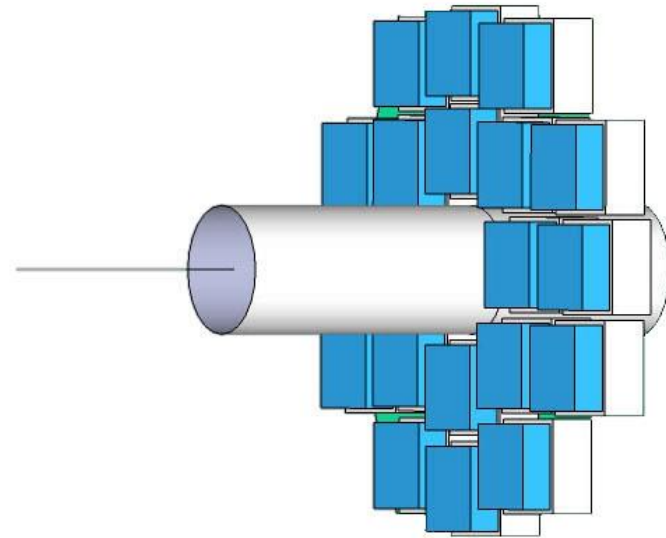


T0 & V0 → FIT (T0+)

T0 and V0
now



Upgraded
detectors



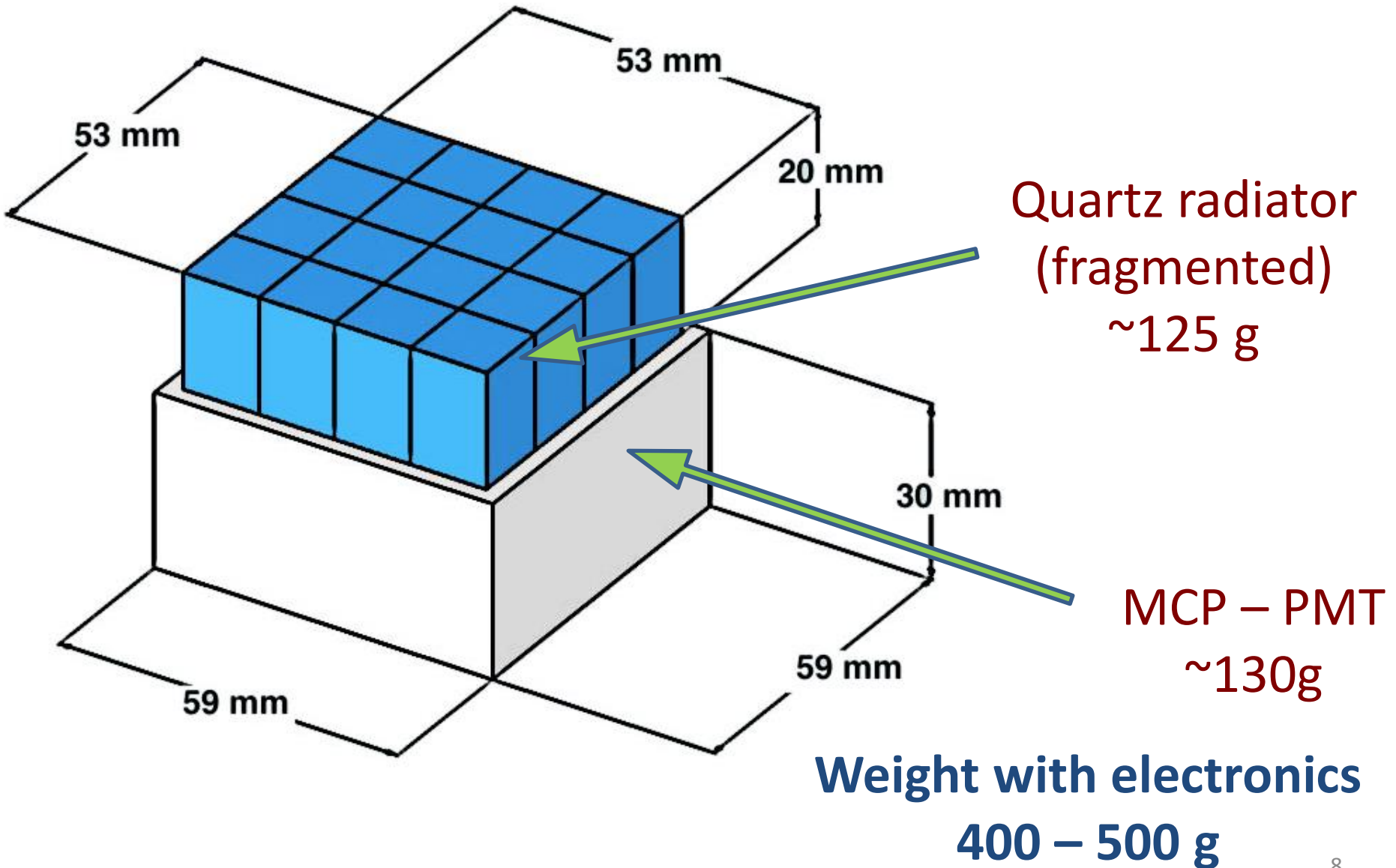
Efficiency comparison

	A	C	A&C	A C
pp @ 14 TeV				
V0*	0.88	0.88	0.83	0.93
T0-Plus*	0.89	0.89	0.84	0.94
$R_{min}=50$ mm				
T0-Plus*	0.88	0.88	0.83	0.93
$R_{min}=60$ mm				
T0-Plus	0.88	0.86	0.80	0.93
Detailed geometry				
$R_{min}=60$ mm				
PbPb @ 5.5 TeV ($b>13$ fm; 70-100% centrality)				
T0-Plus	0.97	0.98	0.95	0.996
Detailed geometry				
$R_{min}=60$ mm				

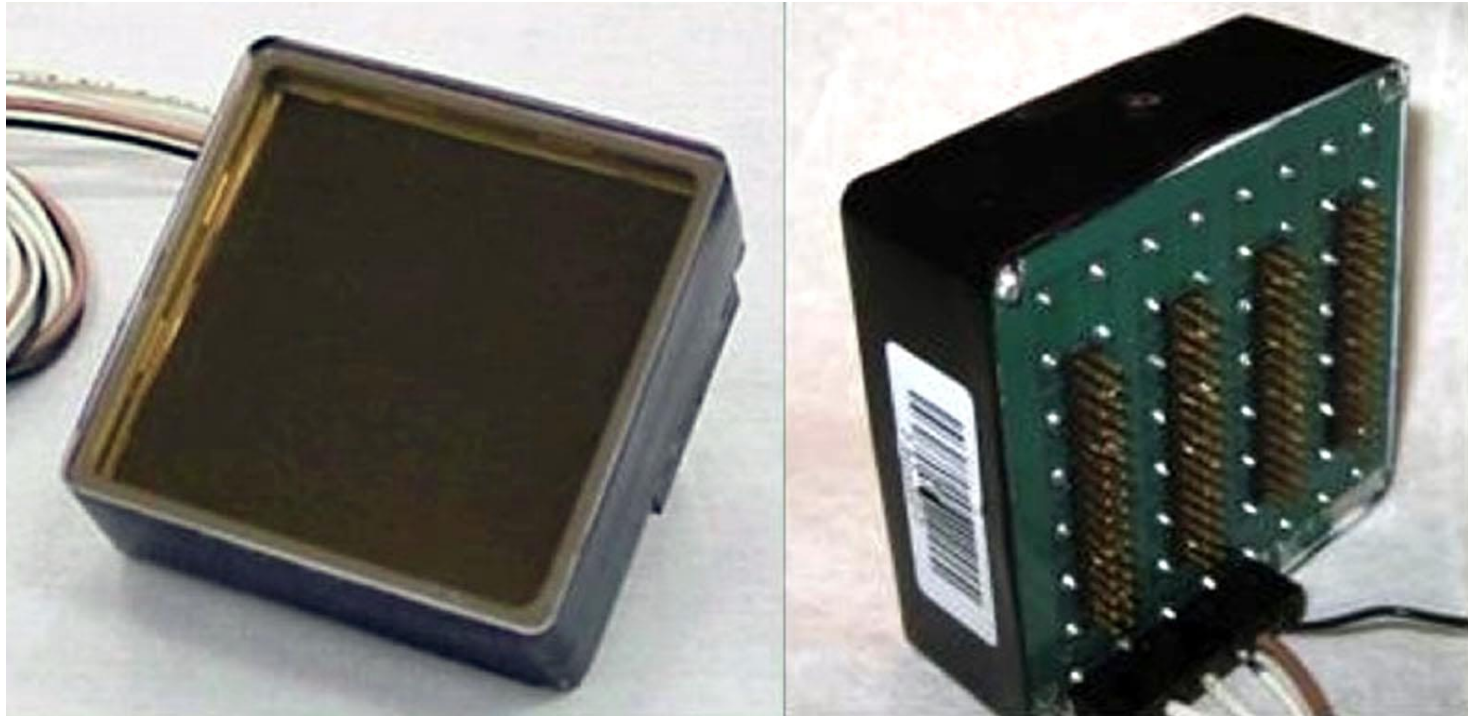
Table 10.1: Efficiency comparison between the current V0 and the proposed T0-Plus. Asterisks indicates that the simulations were done using a simplified geometry.

T0-Plus detector unit

(shown dimensions are without the protective housing nor cabling)



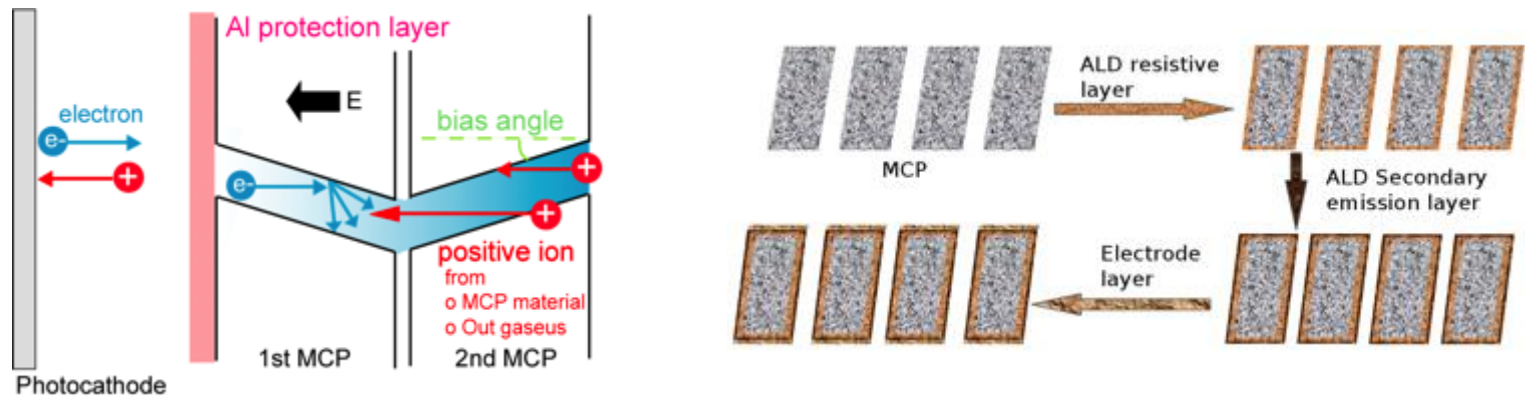
Photonis PLANACON[®] XP85012 or XP85112



Big progress in MCP technology

(since the initial R&D for ALICE)

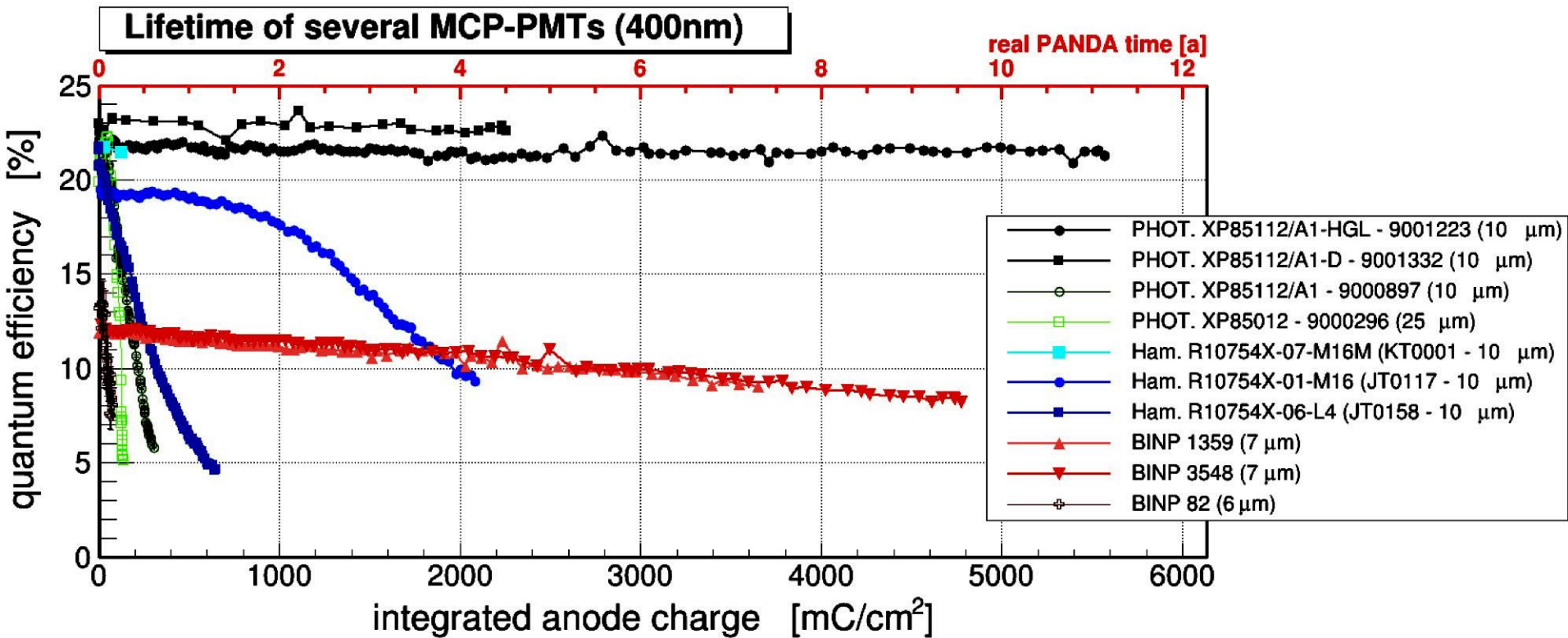
- Appearance of commercially available MCP-PMTs (Hamamatsu, Photonis USA, BINP)
- Significant and ongoing improvement in lifetime:
 - Atomic Layer Deposition technology [NIM A639 (2011) 148]



- Modified photocathodes [JINST 6 C12026 (2011)]
- Reduced outgassing (borosilicate glass)

For more information: Albert Lehmann, 12th Pisa Meeting on Advanced Detectors, May 2012

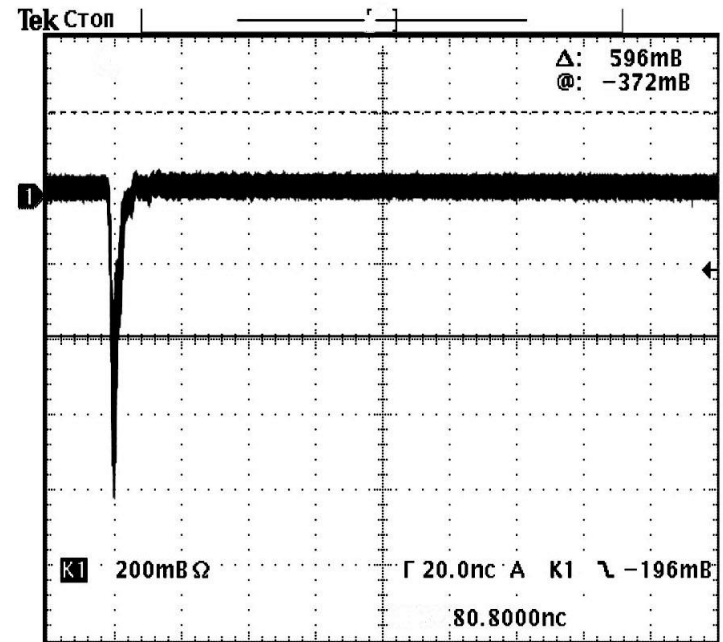
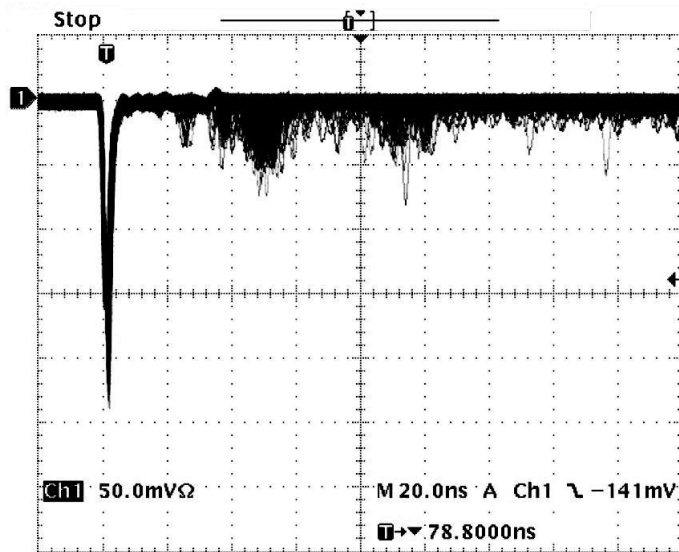
Reliability and lifetime



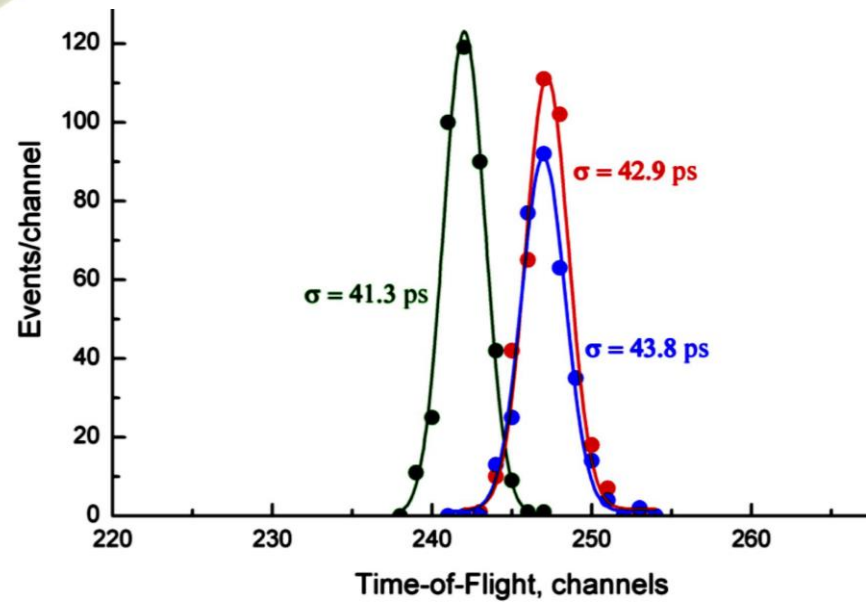
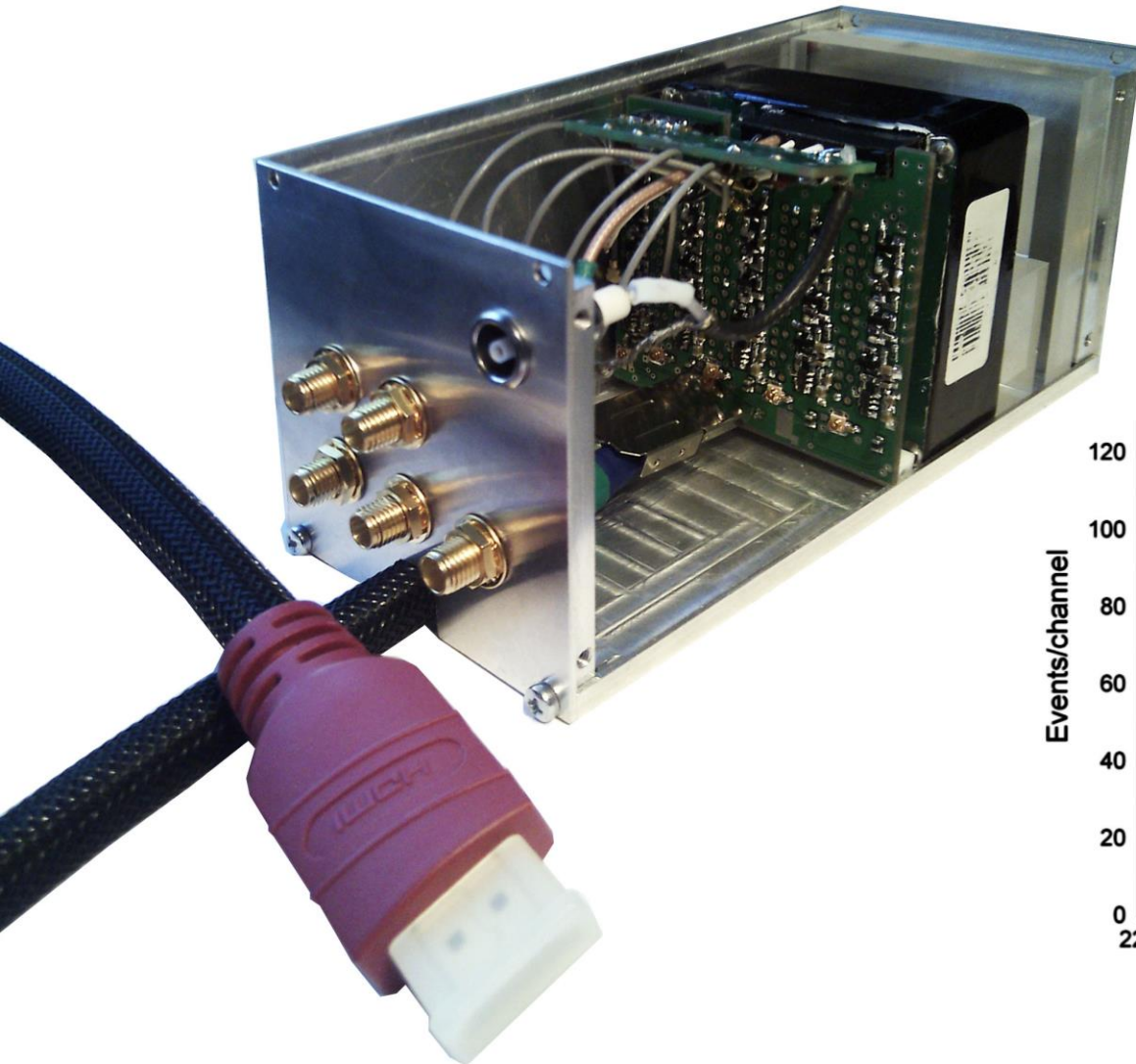
Dependence of the Quantum Efficiency on the Integrated Anode Charge for a variety of MCP-PMT sensors measured by PANDA collaboration. The performance of the ALD treated samples from Photonis USA is shown by the top curves.

A. Lehmann. Lifetime measurements of MCP-PMTs. DIRC2013: Workshop on fast Cherenkov detectors, Giessen Sept 4, 2013.

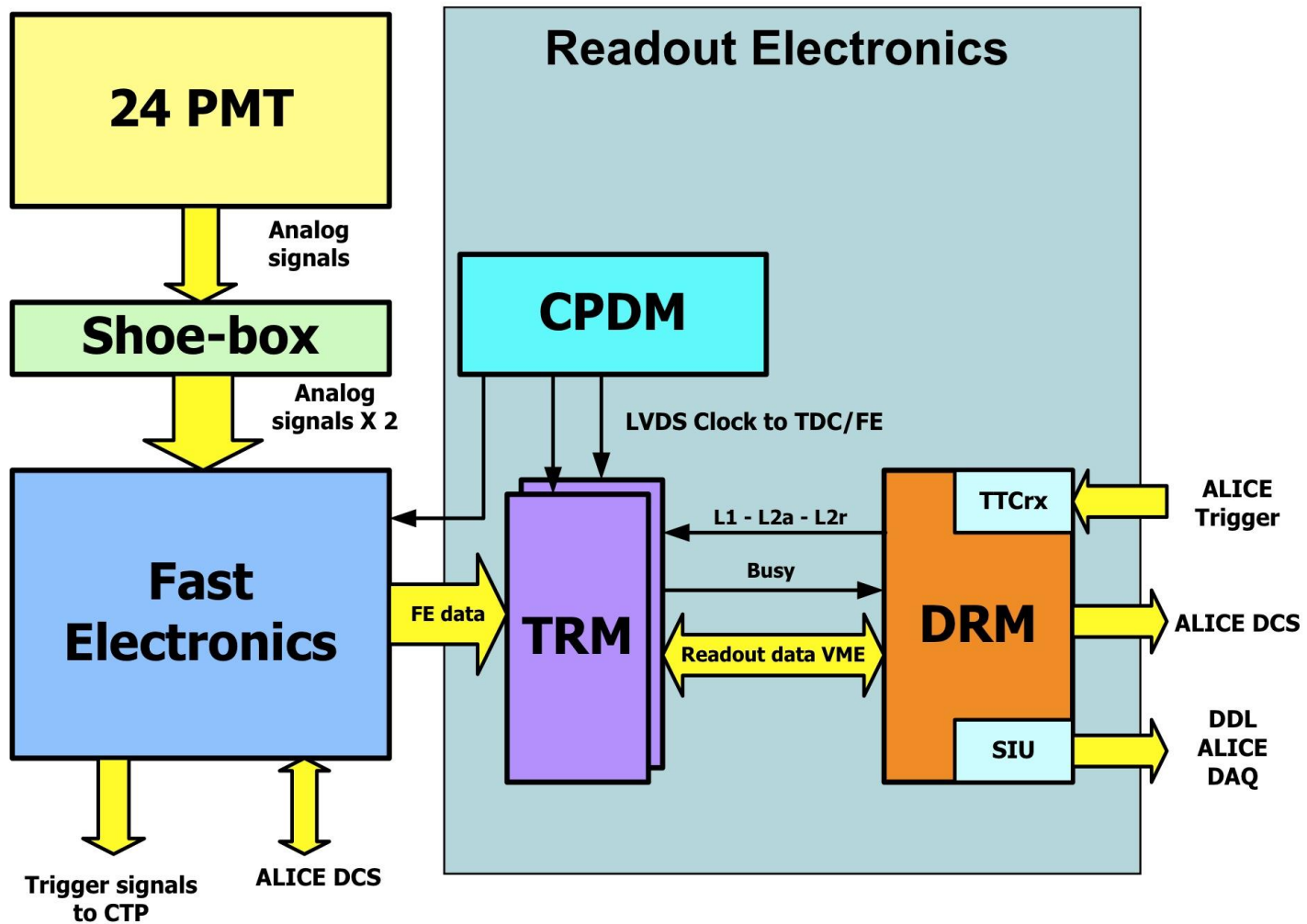
PMT (T0) vs. MCP-PMT (T0-Plus)



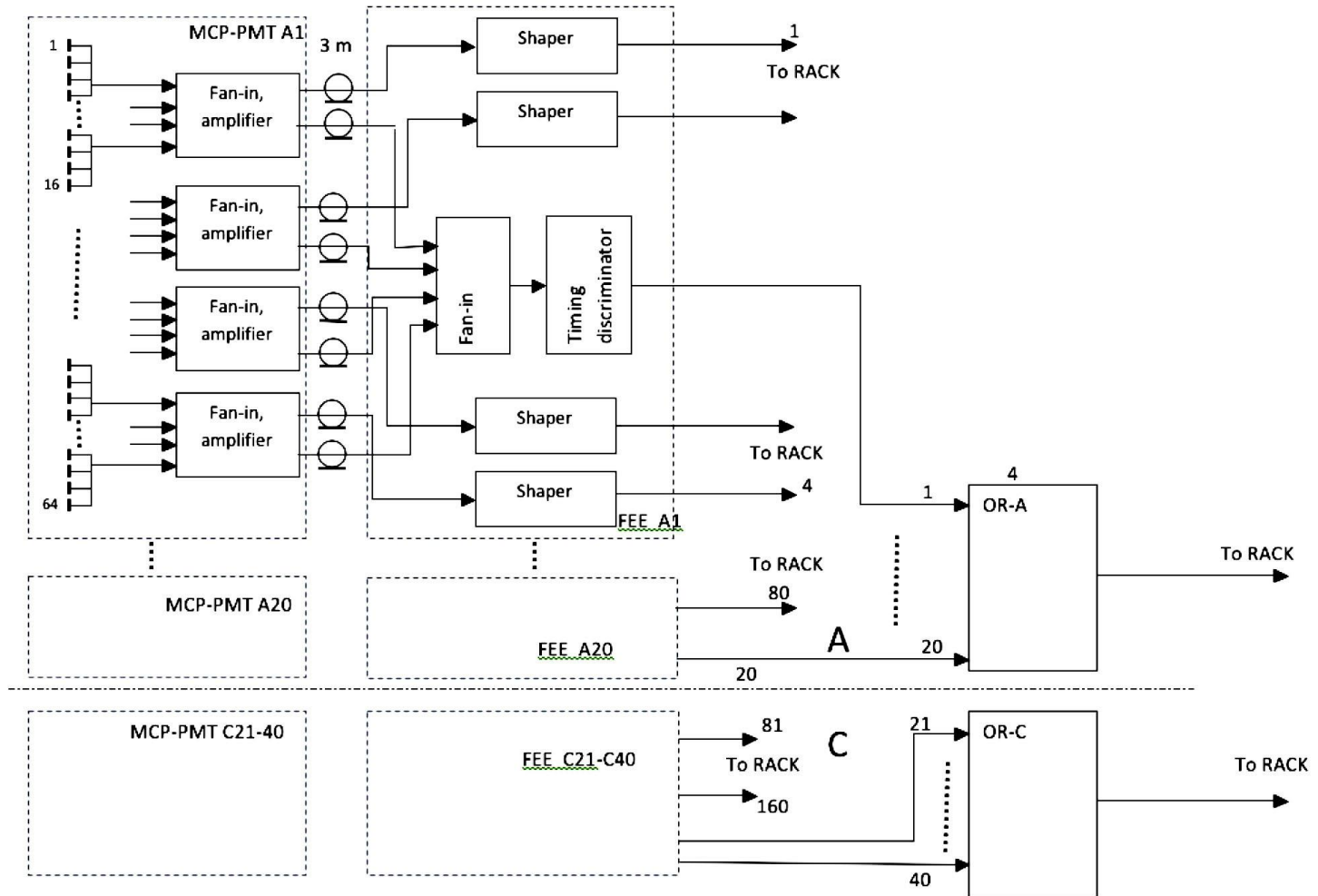
Prototype of MCP-PMT based detector module (NIKA)



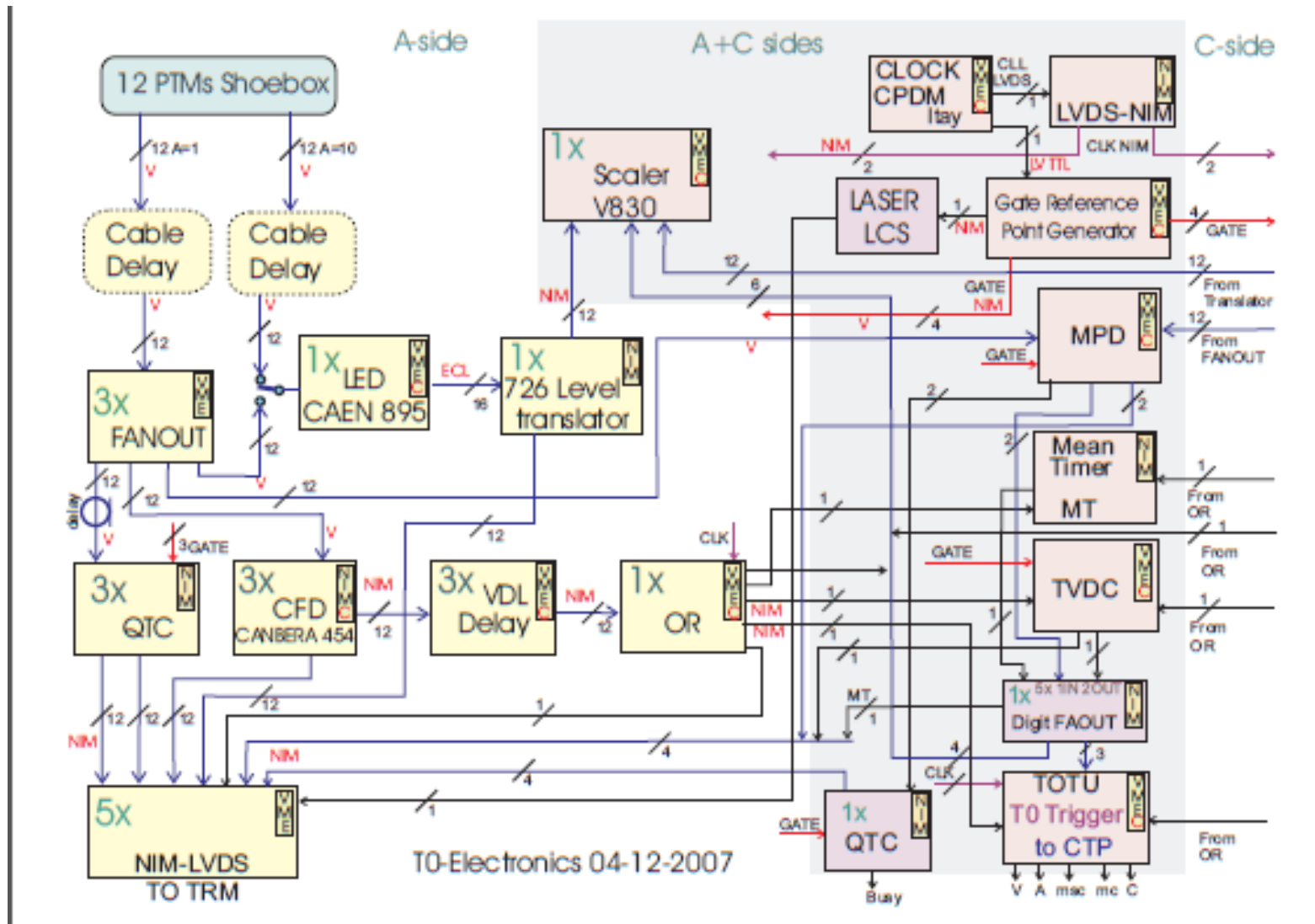
FIT electronics and readout will follow the T0/TOF solution



First draft of shoebox/preamp stage for FIT



T0/FIT fast electronics



FIT cost

T0-Plus	[kCHF]
MCP-PMT	500
Readout electronics	480
Services and Mechanics	40
T0-PlusTotal	1020

FIT Institutes

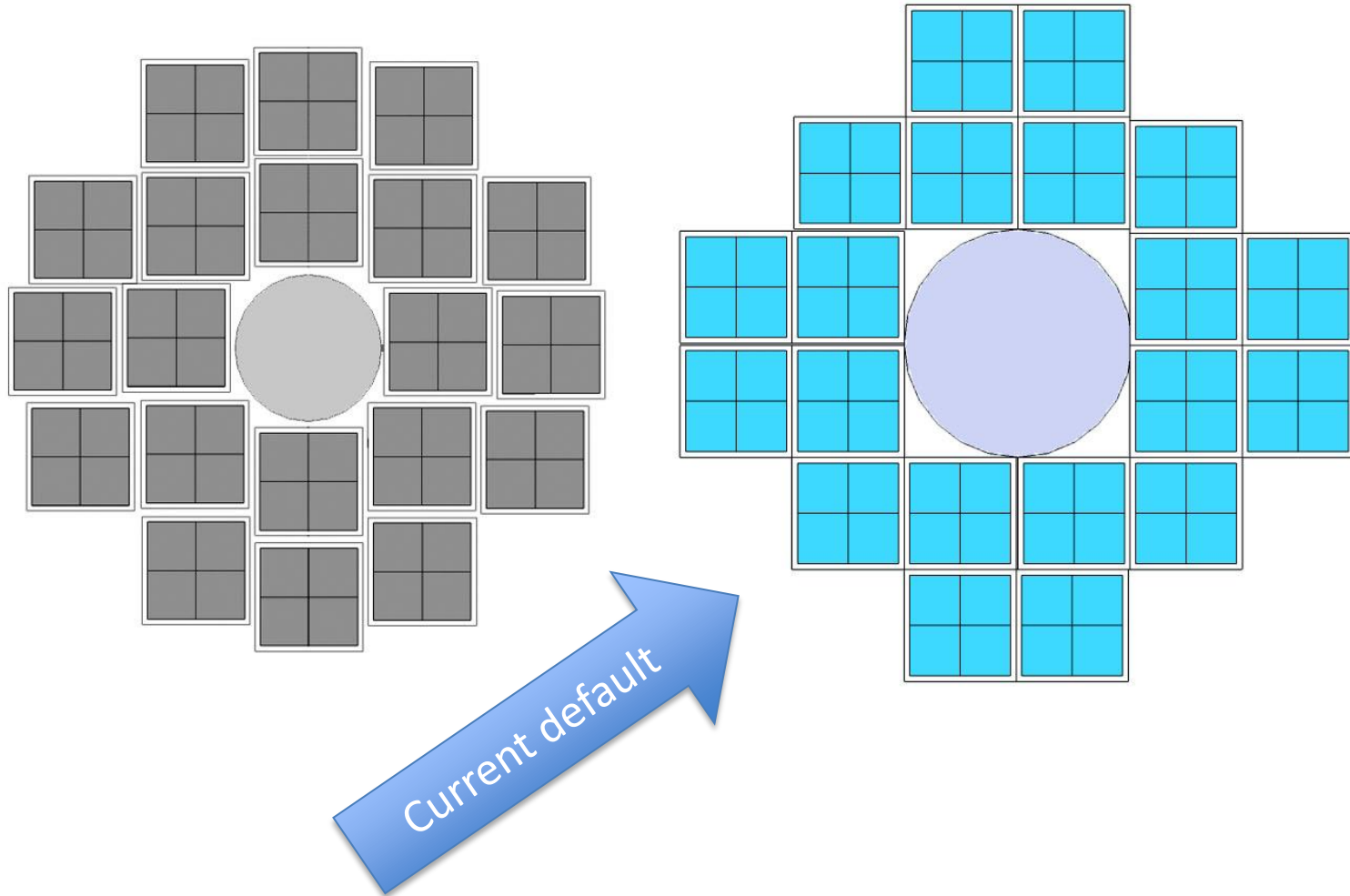
1. Chicago State University, Chicago, United States
2. Helsinki Institute of Physics (HIP) and University of Jyväskylä, Jyväskylä, Finland
3. Institute for Nuclear Research / Academy of Sciences, Moscow, Russia
4. Moscow Engineering Physics Institute, Moscow, Russia
5. Niels Bohr Institute, University of Copenhagen, Copenhagen, Denmark
6. Russian Research Centre Kurchatov Institute, Moscow, Russia

FIT schedule

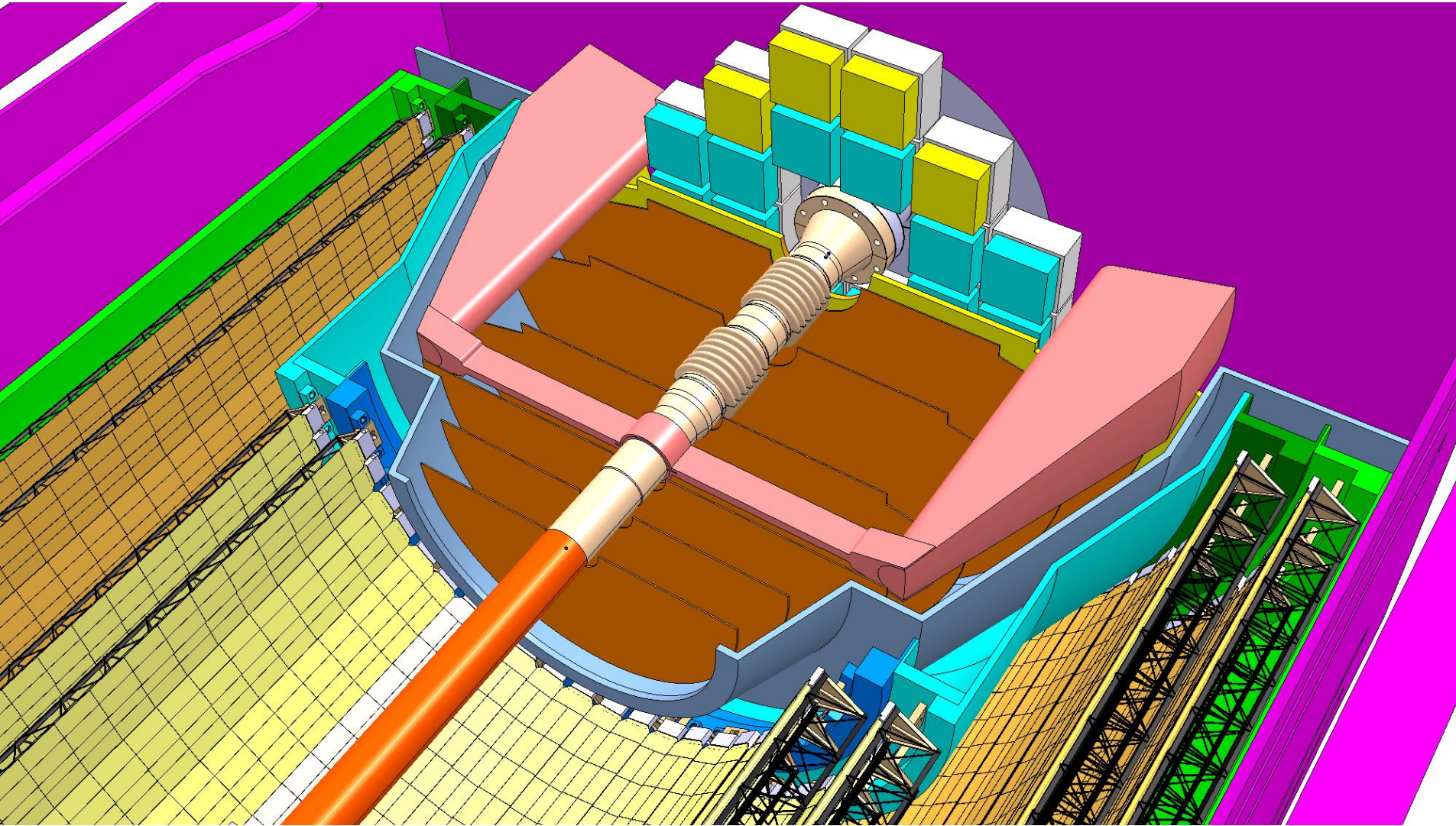
- **2013-2016** prototyping of detector modules and electronics; in-beam tests
- **2017** Purchase of MCP-PMT sensors and assembly of detector modules and electronics
- **2018** FIT installation

Considered configurations on the C-side

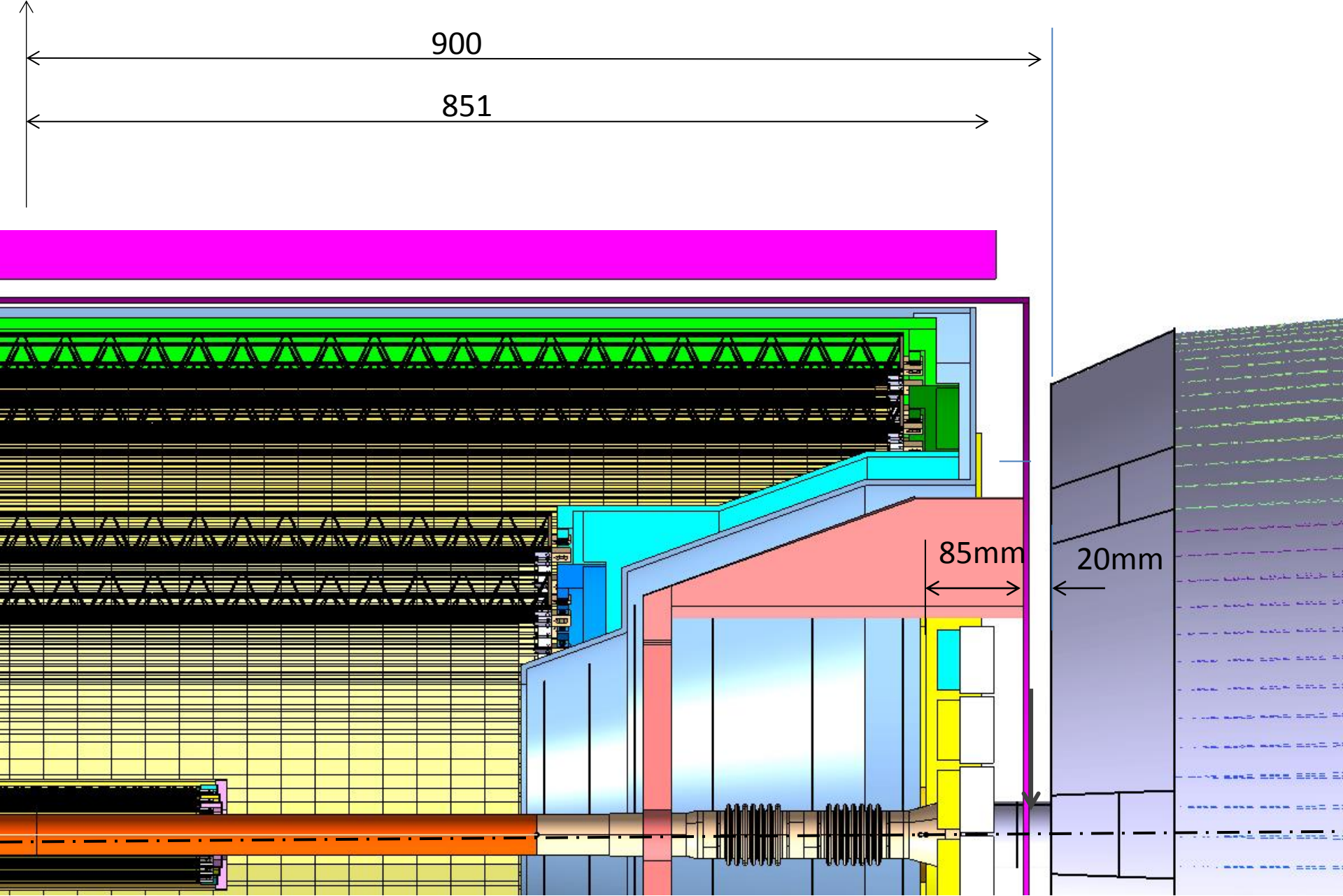
$R_{\text{MIN}} \cong 5 \text{ cm}$ vs. $R_{\text{MIN}} \cong 6 \text{ cm}$
(20 detector modules)



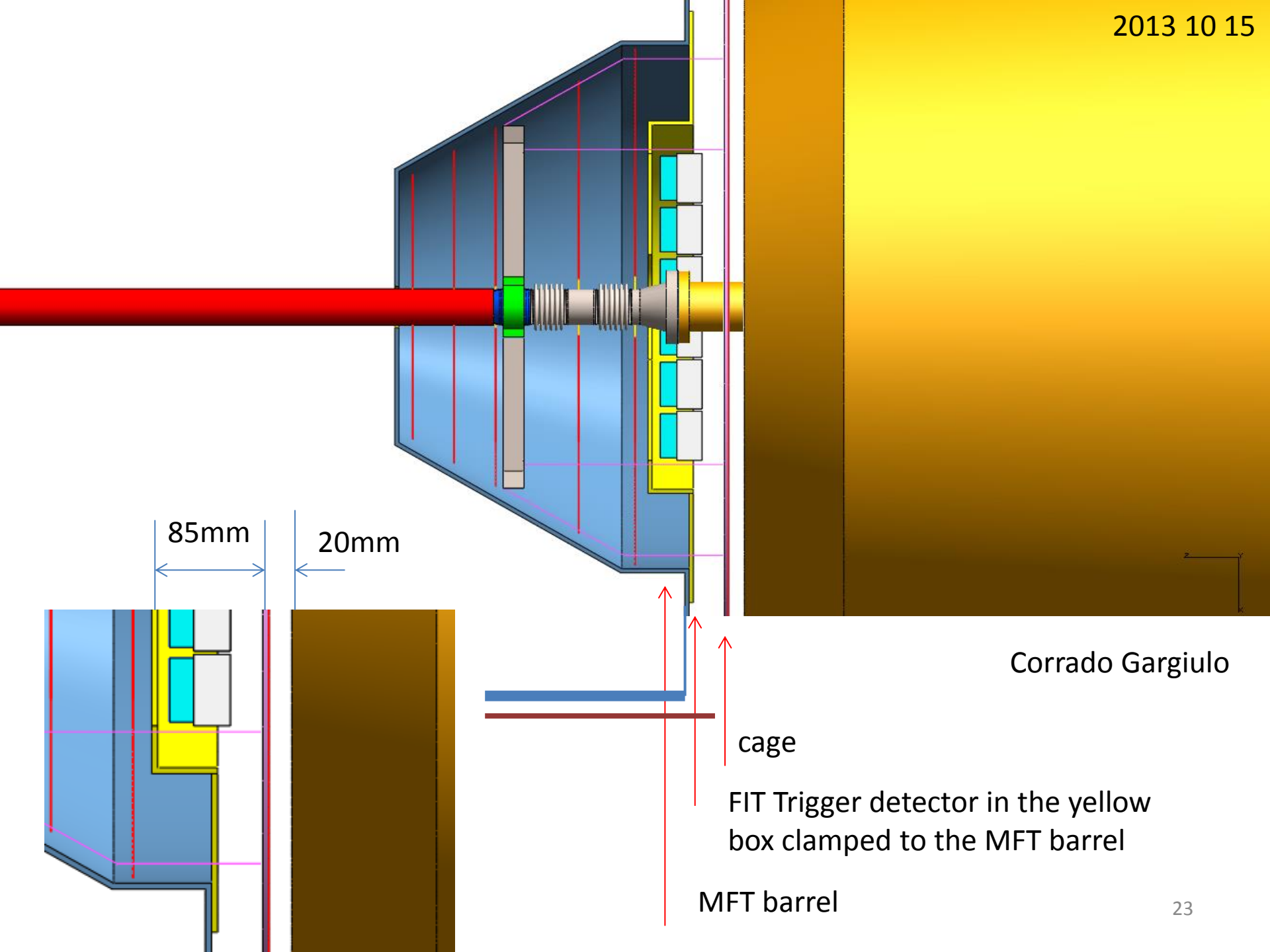
Integration on the C-side (ITS, MFT, FIT)



Corrado Gargiulo



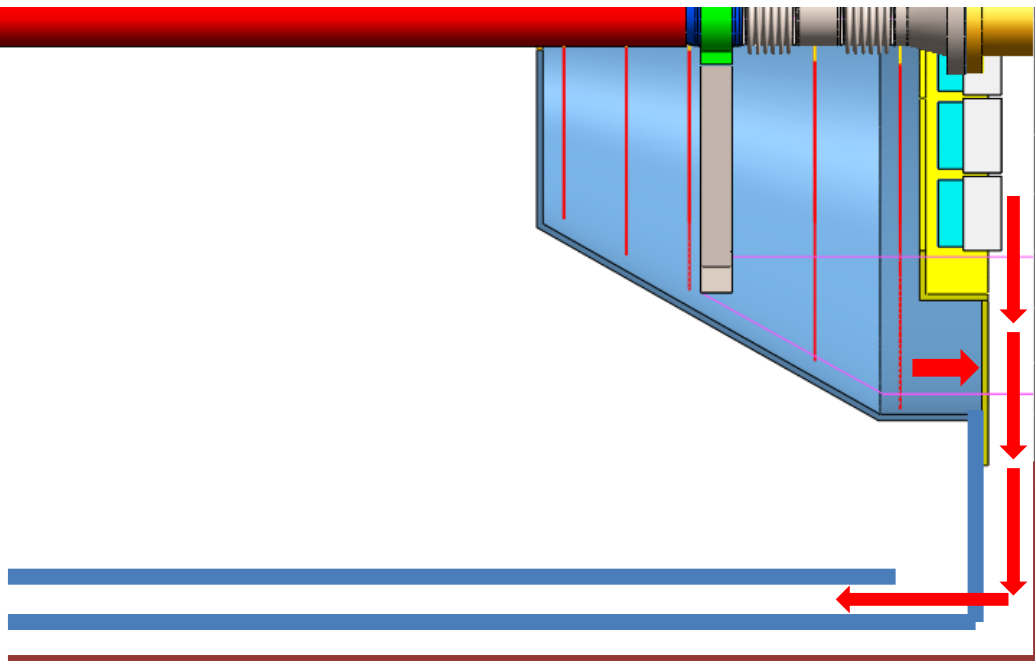
Corrado Gargiulo



Corrado Gargiulo

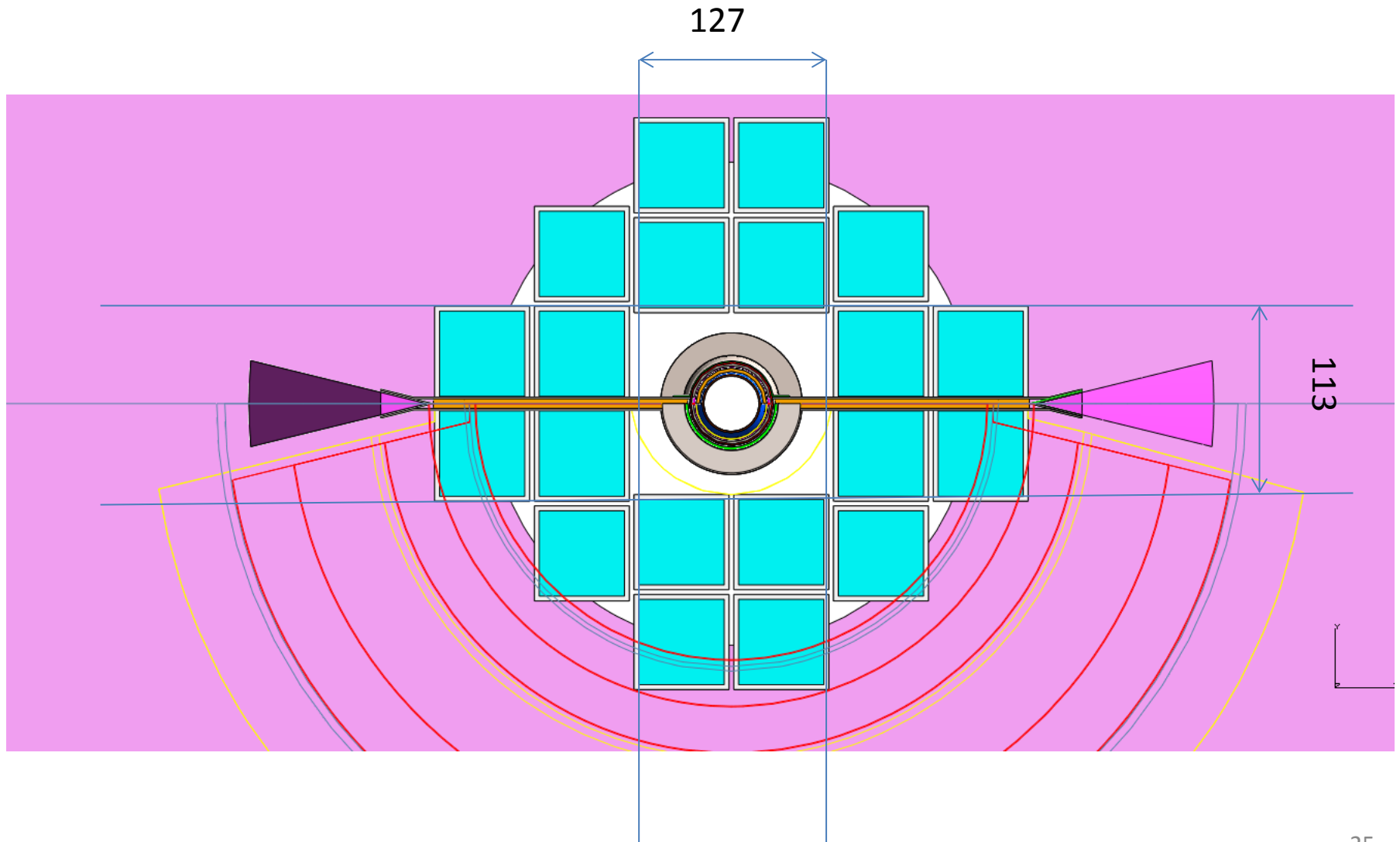
- cage
- FIT Trigger detector in the yellow box clamped to the MFT barrel
- MFT barrel

FIT-C services would go to A-side

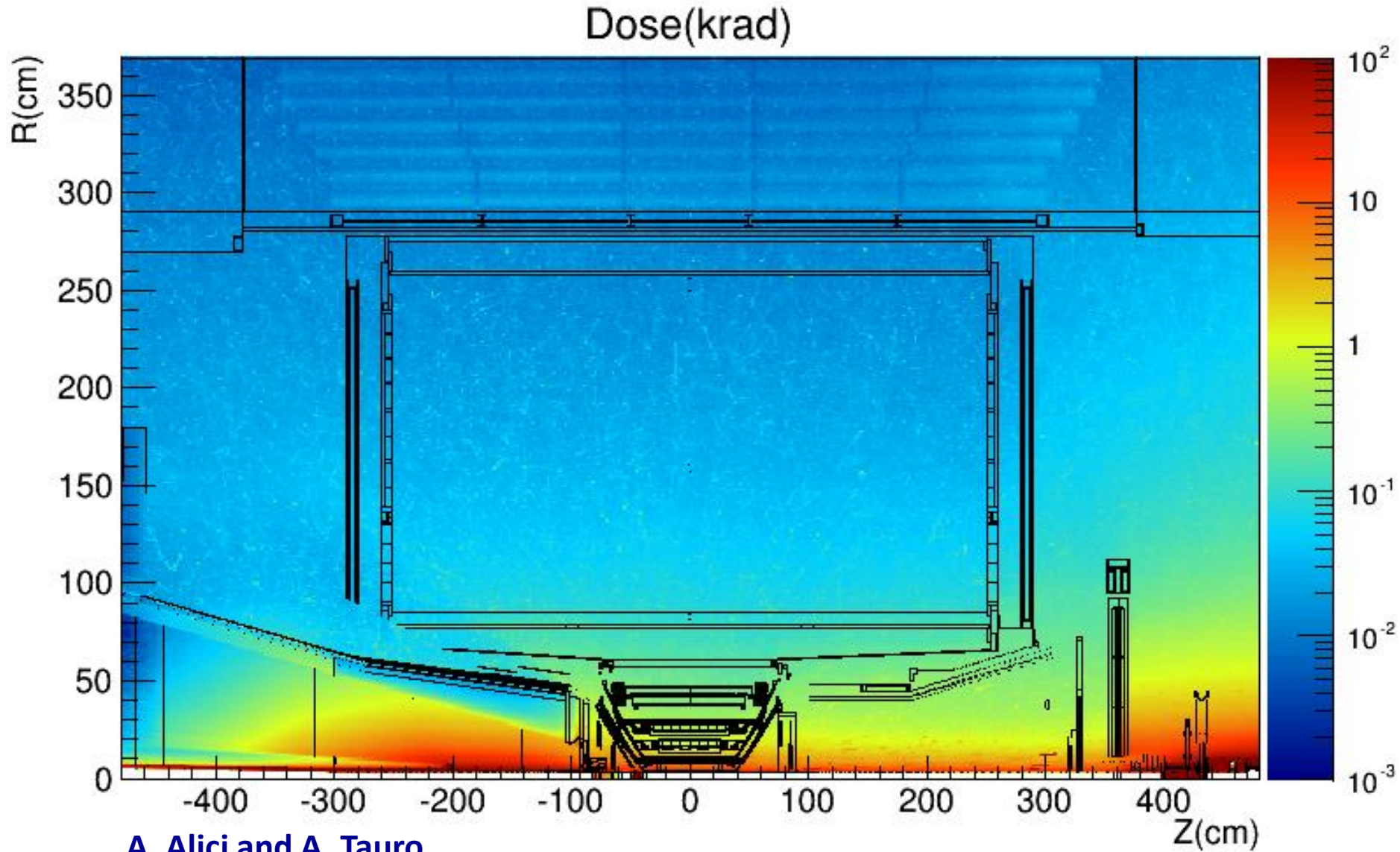


Corrado Gargiulo

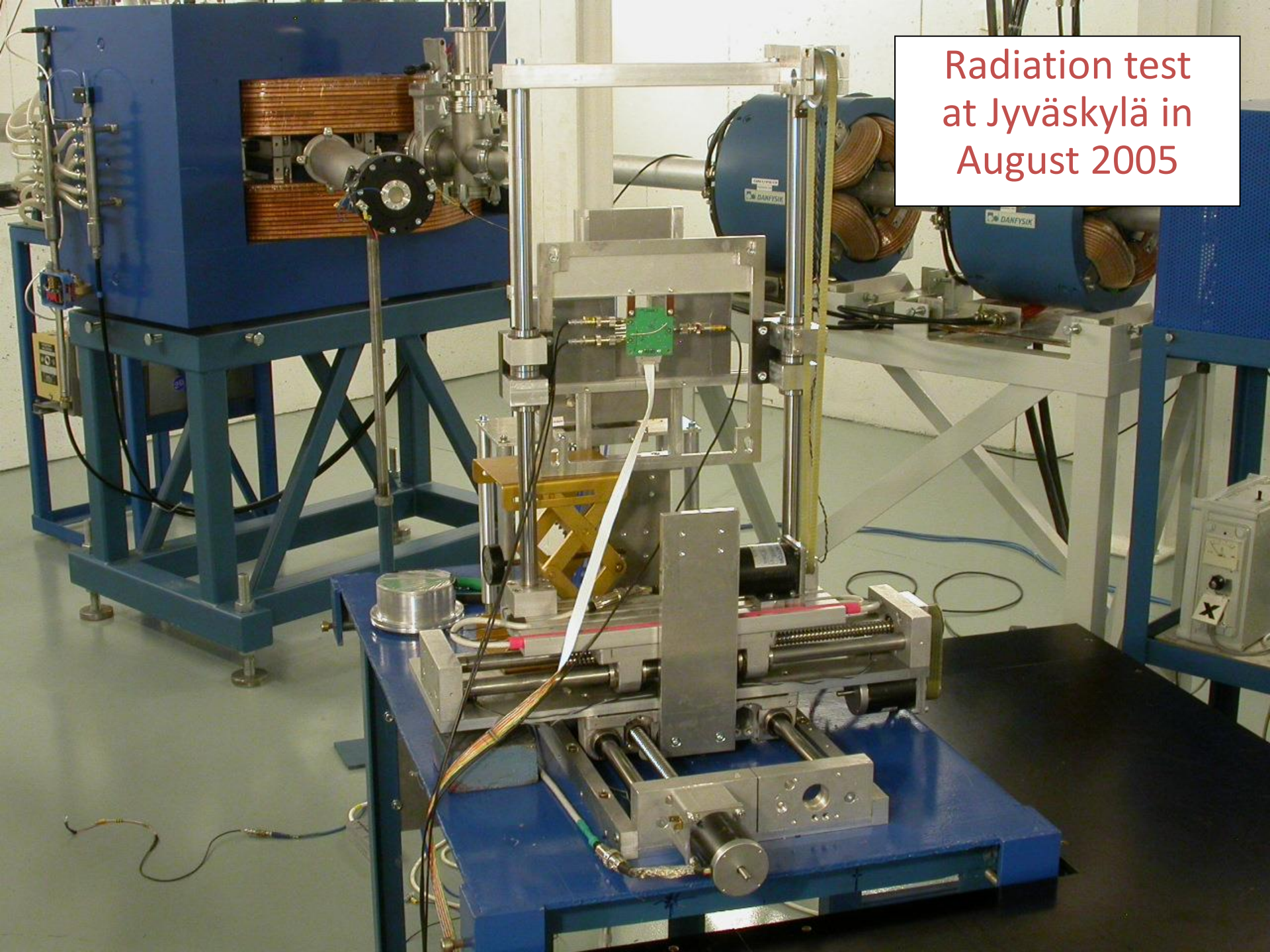
Current default configuration (imposed by MFT boundary conditions)



Expected dose during Run3

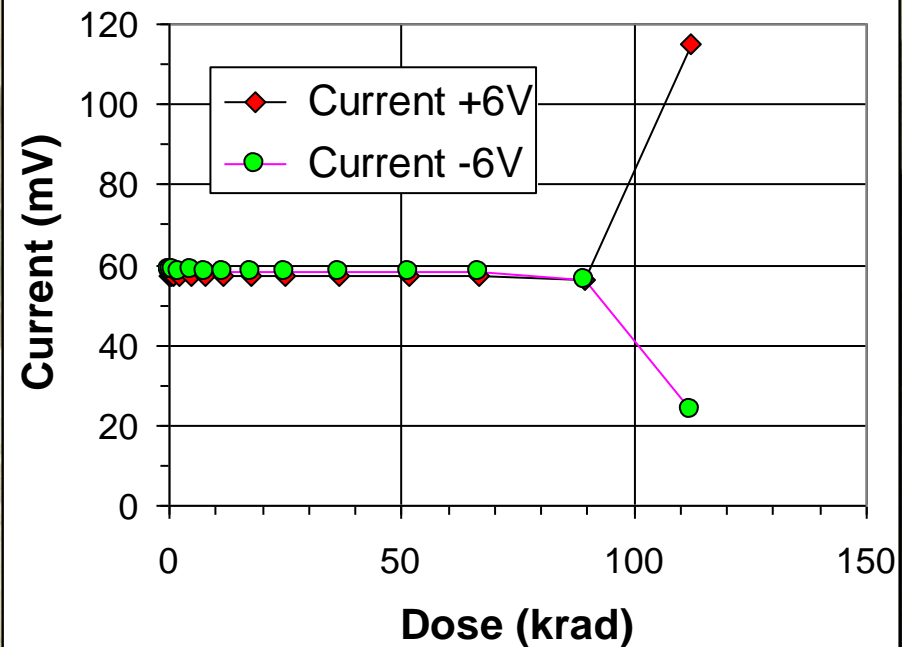
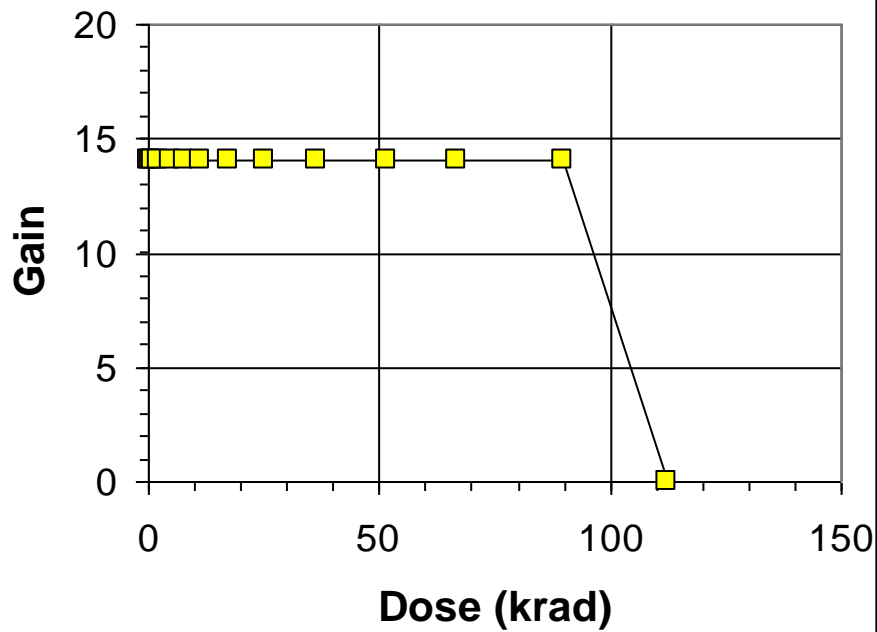


Radiation test
at Jyväskylä in
August 2005

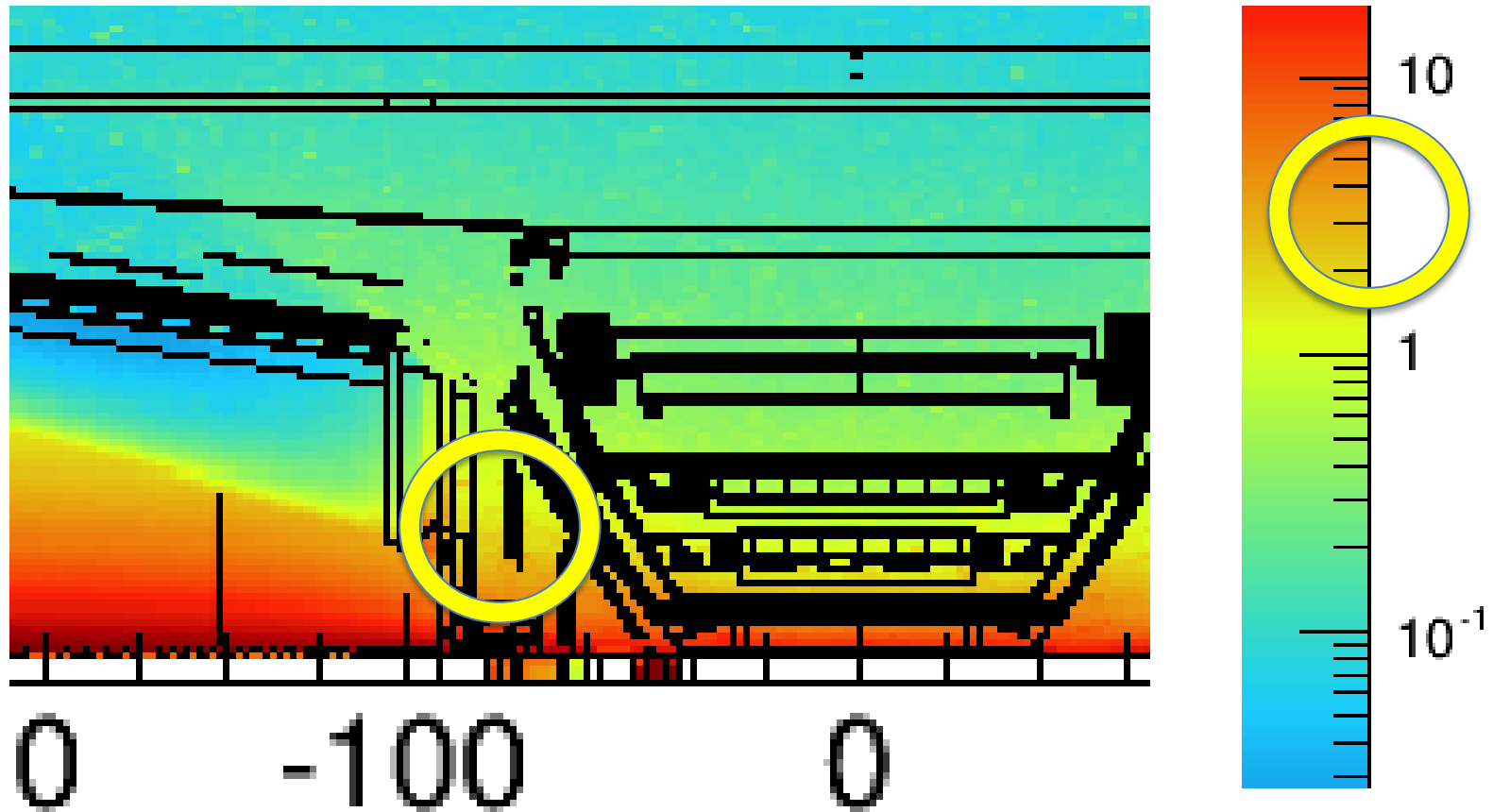


LDO Voltage Regulator
UCC284DP-5
(Texas Instrument)

Broken at ~100 krad exposure



Expected Run3 dose
in the sensor region is < 10 krad



Bandwidth calculations

Detector & Collision type/Event type	Hits/event	TRM x crate	Word x TRM	HPTDC readout (μ s)	Maximum rate due to HPDTC (kHz)	Crate payload (bytes)	Input Trigger Rate (kHz)	DDL Bandwidth (MB/s)	VME Bandwidth (MB/s)
Empty	0	10	6	3.8	263	296	200	59.2	48
Empty	0	10	2	3.8	263	136	200	27.2	16
TOF HM PbPb	10000	10	36	6.8	147	1496	50	74.8	72
TOF MB PbPb	2000	10	12	4.4	227	536	50	26.8	24
TOF MB pp	100	10	7	3.9	256	336	200	67.2	56
FIT HM PbPb	160	8	66	9.8	102	2168	50	108.4	105.6
FIT MB PbPb (0-80% centrality)	160	8	66	9.8	102	2168	50	108.4	105.6
FIT MB pp	25	8	16	4.8	208	568	200	113.6	102.4

Pietro Antonioli

TRM Empty readout [μ s]	3.8
DRM words (CDH + TOF)	14
Single hit readout [μ s]	0.1

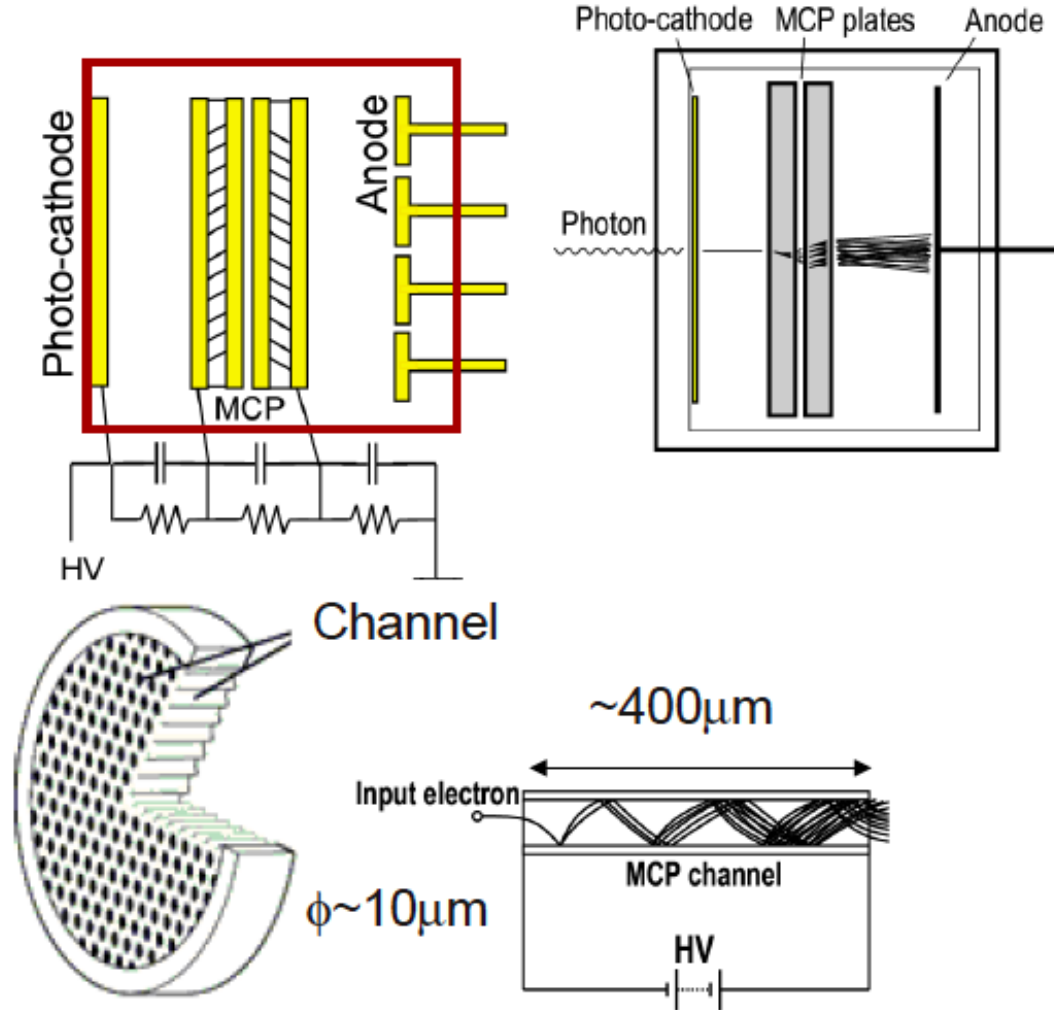
TO-Plus (40 modules; 160 segments) is already close to the bandwidth limit of one crate readout system! Increasing of the segmentation or adding of the second detector (V0-Plus) would require the second crate (brute force approach) or a new/clever way of processing the input data.

Thank you for your attention!

Fast Interaction Trigger

BACK UP SLIDES

Microchannel-Plate PMT



Photonis PLANACON[®]

XP85012 or XP85112



Cost (2012):

XP85012/A1-Q - \$8,830

XP85112/A1-Q - \$14,900

Datasheet available at:

http://www.photonis.com/attachment.php?id_attachment=40

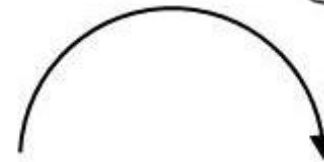
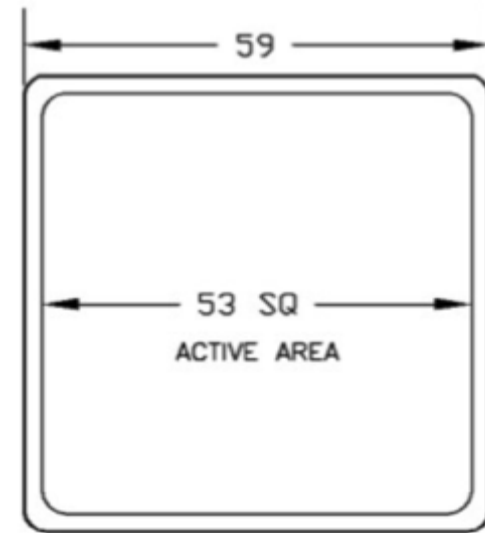
XP85012

PLANACON[®]



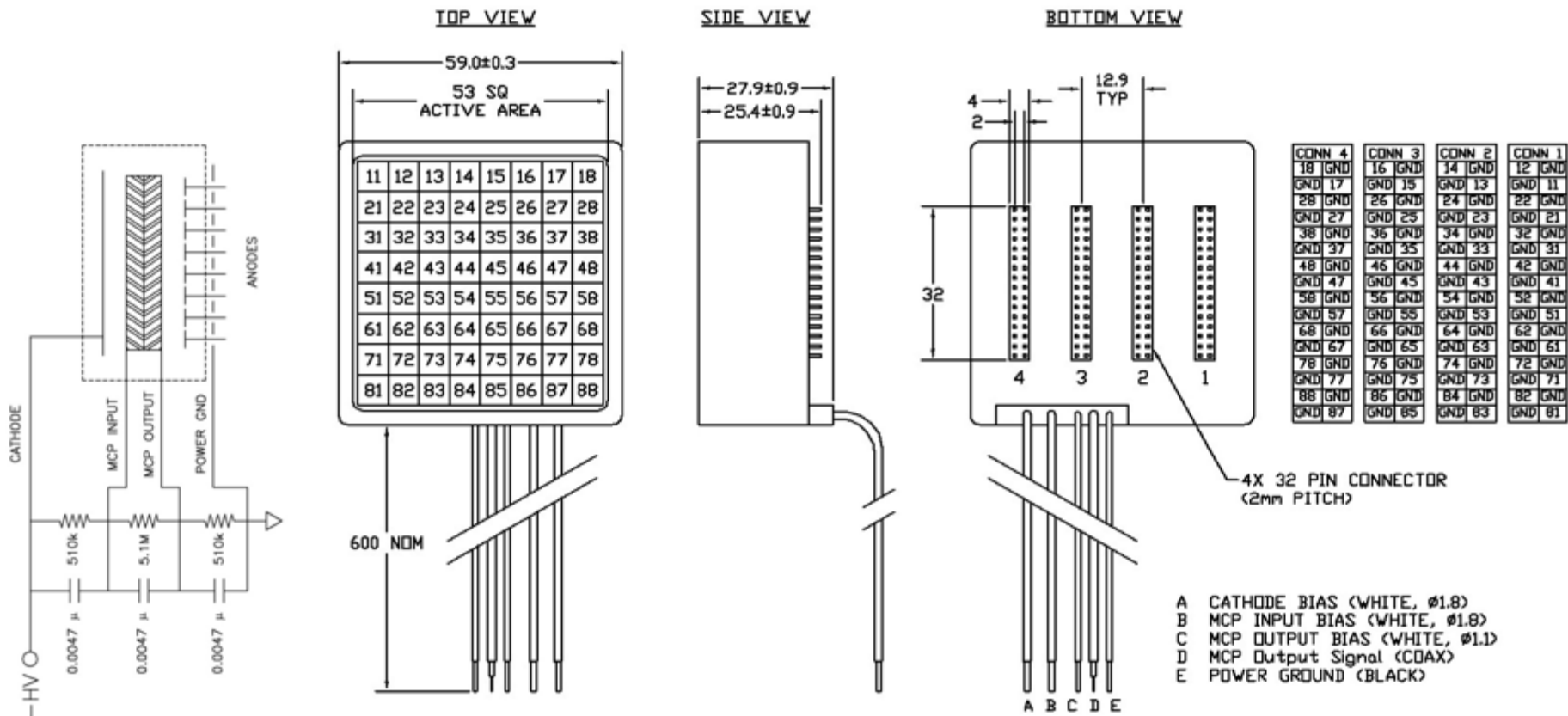
Window-side

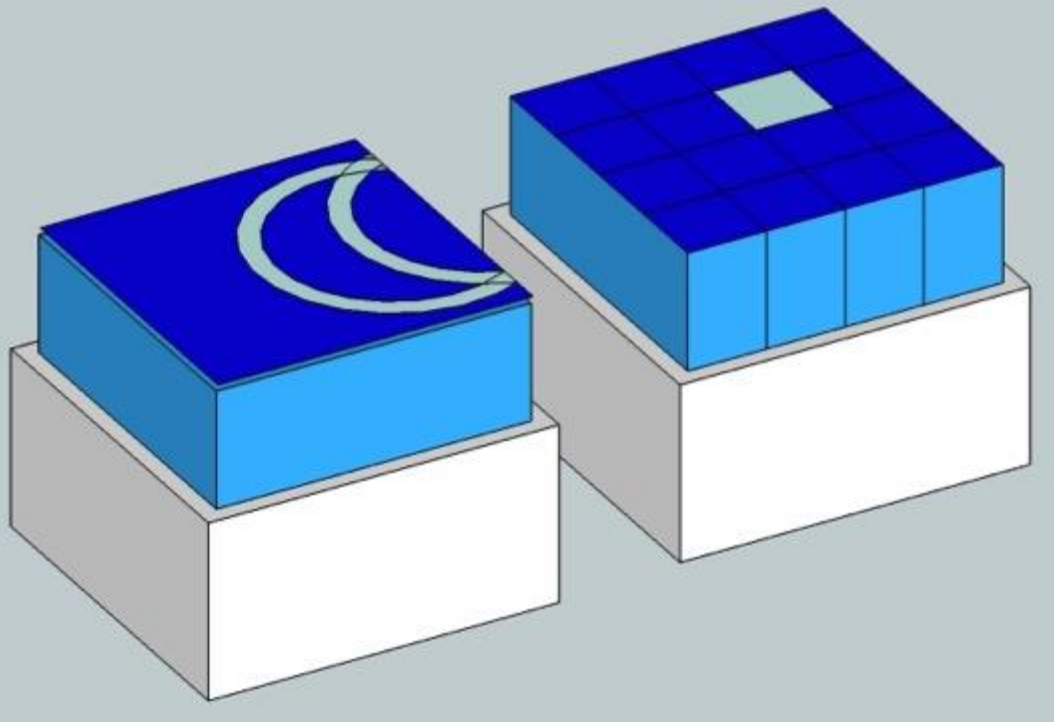
Overall thickness ~30 mm



Back-side

The anode of **XP85012** is **subdivided into 64 units**. This feature, together with fragmented radiator, could be used to **improve performance and add tracking ability to T0**





Solid vs. fragmented quartz radiator

In case of a **solid radiator** the Cherenkov ring of light generated by a MIP spreads over a large surface of the light sensitive element. To register that diffused light, **higher amplification (HV)** is required.

The inner walls of a **fragmented radiator** reflect the light and contain it within the sub-unit of the radiator. As a result the light intensity falling on the MCP surface is higher. Therefore **lower amplification (HV)** is needed.